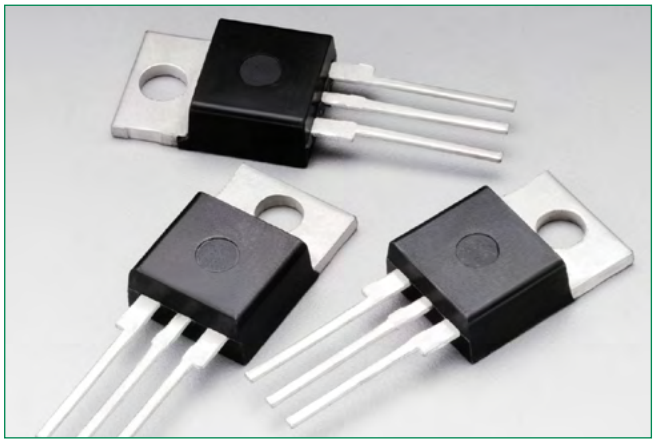
BTB12-600BW3G, BTB12-800BW3G

Surface Mount – 800V



Description

The BTB12 is designed for high performance full-wave AC control applications where high noise immunity and high commutating di/dt are required.

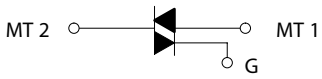
Features

- Blocking Voltage to 800 V
- On-State Current Rating of 12 Amperes RMS at 25°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt – 2000 V/µs minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dI/dt – 4. A/ms minimum at 125°C
- These are Pb–Free Devices

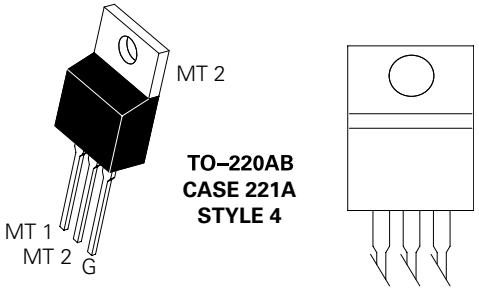
Additional Information

Resources | Accessories | Samples

Functional Diagram



Pin Out



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BTB12-600BW3G, BTB12-800BW3G

Surface Mount – 800V

Maximum Ratings (T_J = 25°C unless otherwise noted)

Rating		Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, T_J = -40° to 125°C)	BTB12–600BW3G BTB12–800BW3G	V_{DRM}, V_{RRM}	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T_C = 80°C)		$I_{T\ (RMS)}$	12	A
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, T_C= 25°C)		I_{TSM}	120	A
Circuit Fusing Consideration (t = 10 ms)		I^2t	78	A^2sec
Non–Repetitive Surge Peak Off–State Voltage (T_J = 25°C, t = 10 ms)		V_{DSM} / V_{RSM}	V_{DSM} / V_{RSM} +100	V
Peak Gate Current (T_J = 125°C, t = 20ms)		I_{GM}	4.0	W
Peak Gate Power (Pulse Width ≤ 1.0 µs, T_C = 80°C)		P_{GM}	20	W
Average Gate Power (T_J = 125°C)		$P_{G(AV)}$	1.0	W
Operating Junction Temperature Range		T_J	-40 to +125	°C
Storage Temperature Range		T_{stg}	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Thermal Characteristics

Rating		Symbol	Value	Unit
Thermal Resistance	Junction–to–Case (AC) Junction–to–Ambient	$R_{\Theta JC}$ $R_{\Theta JA}$	2.3 60	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds		T_L	260	°C

Electrical Characteristics - OFF (T_J = 25°C unless otherwise noted ; Electricals apply in both directions)

Characteristic		Symbol	Min	Typ	Max	Unit
Peak Repetitive Blocking Current (V_D = V_{DRM} = V_{RRM}; Gate Open)	T_J = 25°C	I_{DRM}, I_{RRM}	-	-	0.005	mA
	T_J = 125°C		-	-	1.0	

Electrical Characteristics - ON (T_J = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Typ	Max	Unit
Forward On-State Voltage (Note 2) (I_{TM} = ±17 A Peak)		V_{TM}	–	–	1.55	V
Gate Trigger Current (Continuous dc) (V_D = 12 V, R_L = 30 Ω)	MT2(+), G(+)	I_{GT}	2.5	–	50	mA
	MT2(+), G(–)		2.5	–	50	
	MT2(–), G(–)		2.5	–	50	
Holding Current (V_D = 12 V, Gate Open, Initiating Current = ±100 mA)		I_H	–	–	50	mA
Latching Current (V_D = 24 V, I_G = 60 mA)	MT2(+), G(+)	I_L	–	–	70	mA
	MT2(+), G(–)		–	–	90	
	MT2(–), G(–)		–	–	70	
Gate Trigger Voltage (V_D = 12 V, R_L = 30 Ω)	MT2(+), G(+)	V_{GT}	0.5	–	1.7	V
	MT2(+), G(–)		0.5	–	1.1	
	MT2(–), G(–)		0.5	–	1.1	
Gate Non–Trigger Voltage (T_J = 125°C)	MT2(+), G(+)	V_{GD}	0.2	–	–	V
	MT2(+), G(–)		0.2	–	–	
	MT2(–), G(–)		0.2	–	–	

2. Indicates Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle ≤ 2%.

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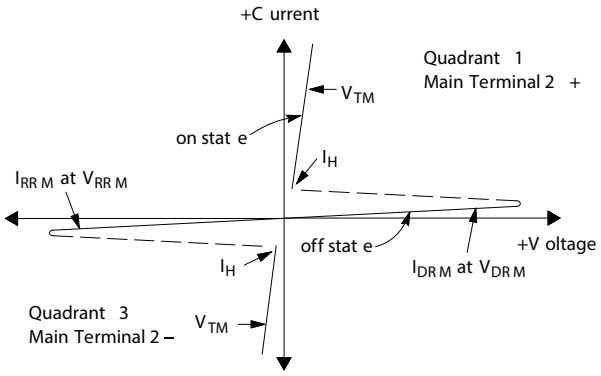
Surface Mount – 800V

Dynamic Characteristics

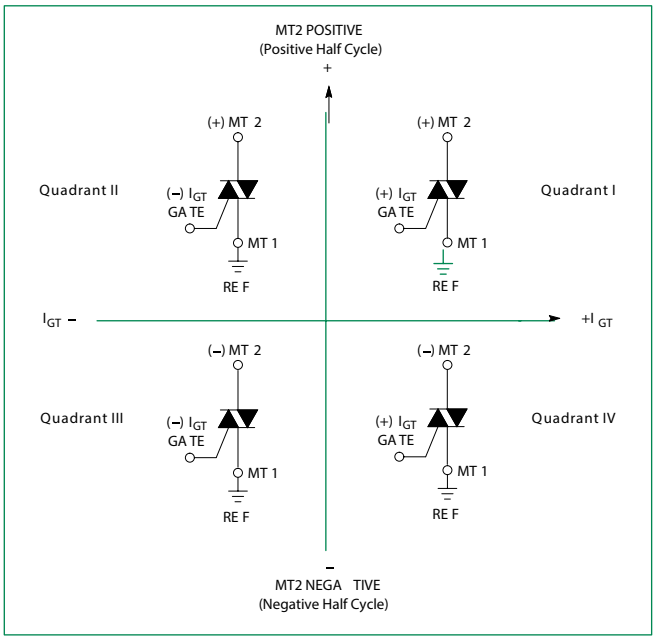
Characteristic	Symbol	Min	Typ	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, T_J = 125°C, No Snubber)	(dI/dt)c	4.0	–	–	A/ms
Critical Rate of Rise of On–State Current (T_J = 125°C, f = 120 Hz, I_G = 2 x I_{GT}, tr ≤ 100 ns)	dI/dt	–	–	50	A/µs
Critical Rate of Rise of Off-State Voltage (V_D = 0.66 x V_{DRM}, Exponential Waveform, Gate Open, T_J = 125°C)	dV/dt	2000	–	–	V/µs

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off State Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Reverse Off State Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Maximum On State Voltage
I_H	Holding Current



Quadrant Definitions for a Triac



All polarities are referenced to MT1.
With in–phase signals (using standard AC lines) quadrants I and III are used

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Surface Mount – 800V

Figure 1. RMS Current Derating

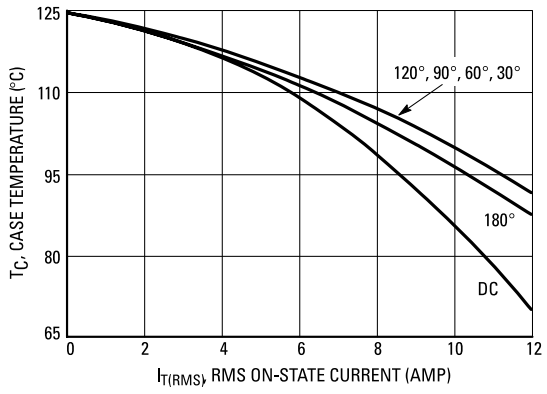

Figure 2. On-State Power Dissipation

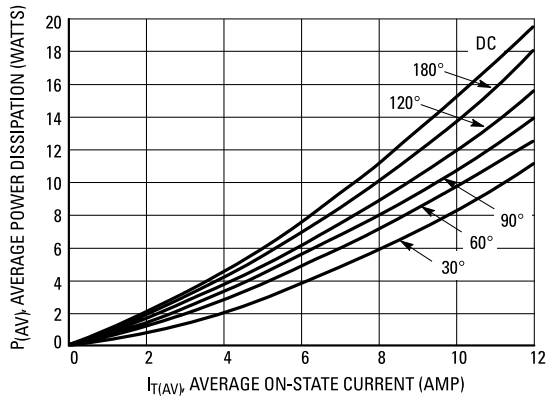

Figure 3. On–State Characteristics

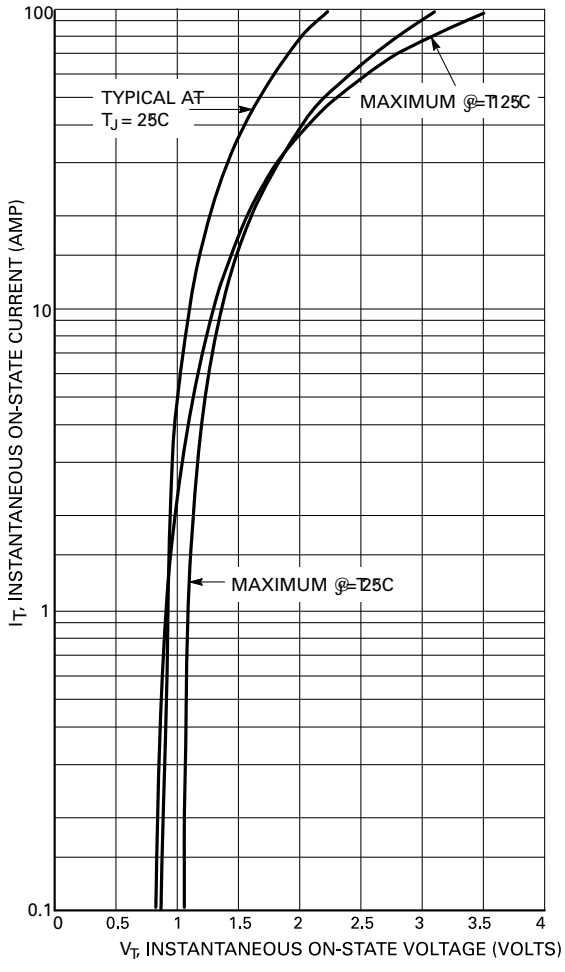

Figure 4. Thermal Response

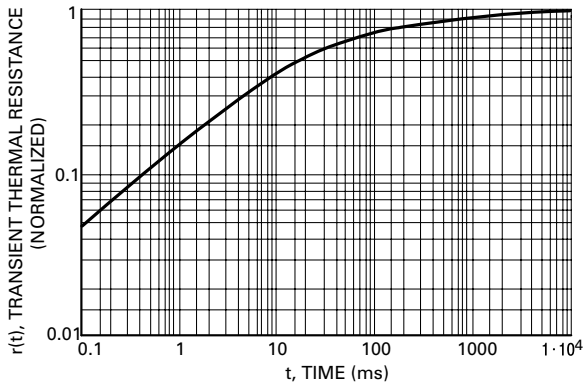

Figure 5. Typical Hold Current Variation

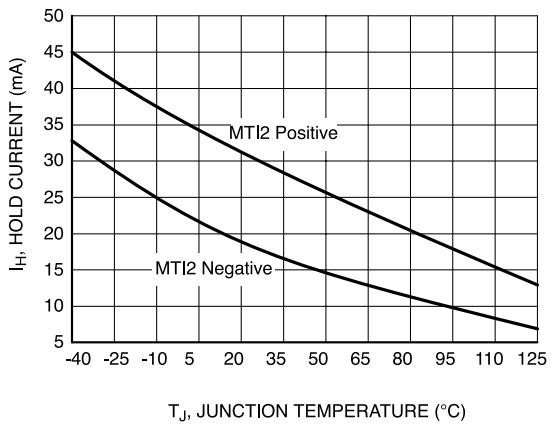

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Figure 6. Typical Gate Trigger Current Variation

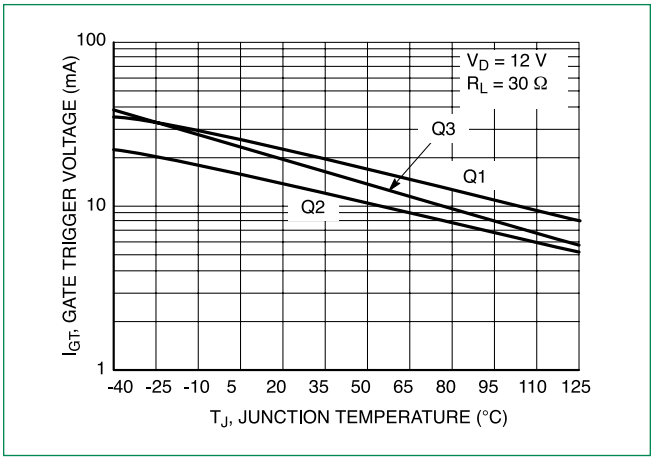


Figure 7. Typical Gate Trigger Voltage Variation

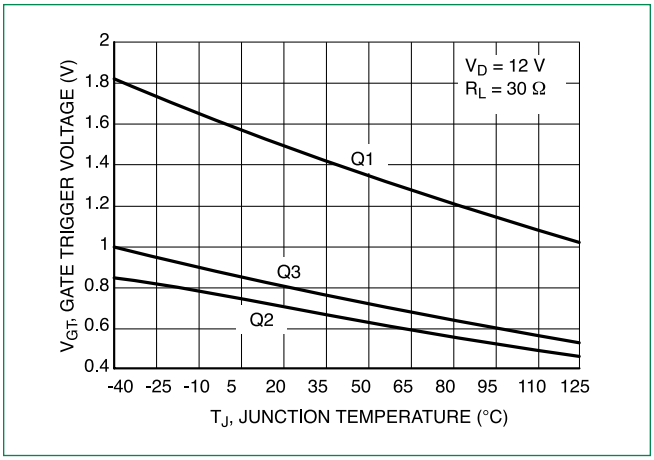


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential Waveform)

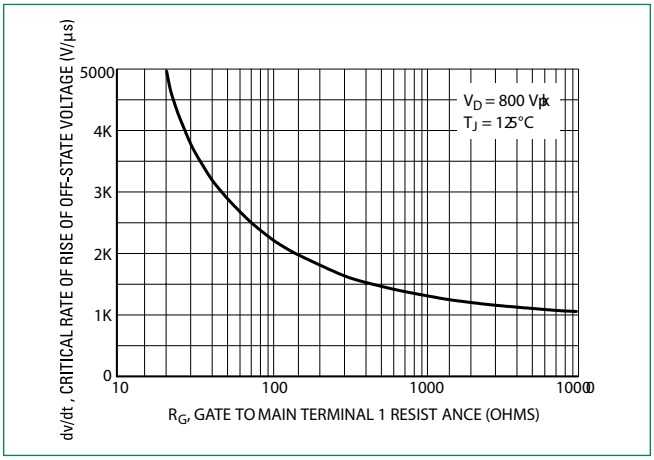
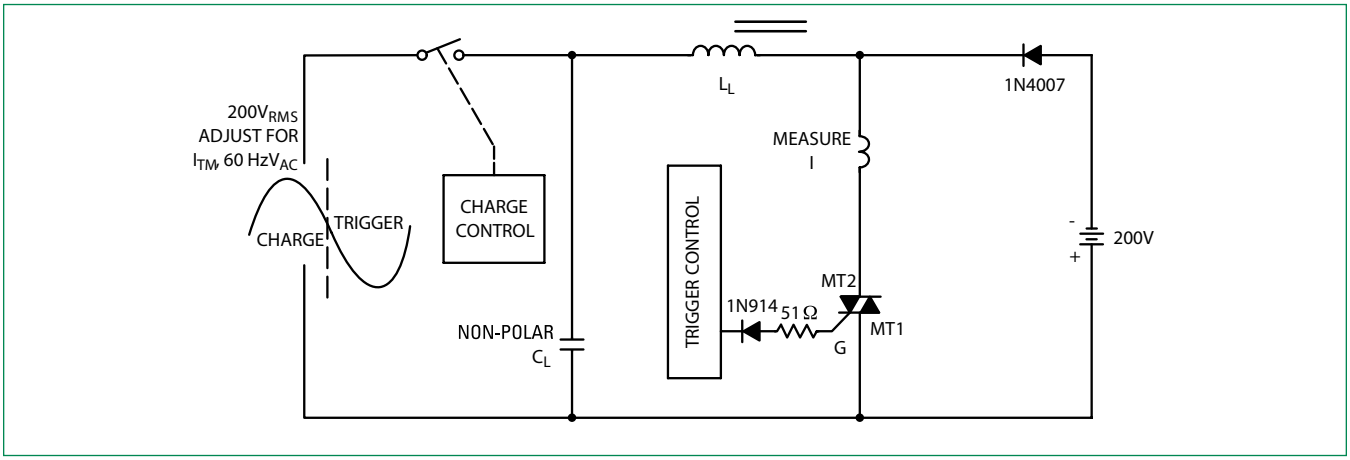


Figure 9. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)



Note: Component values are for verification of rated (di/dt)c. See AN1048 for additional information

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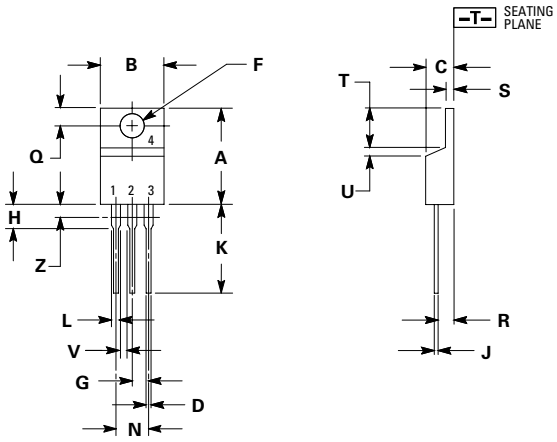
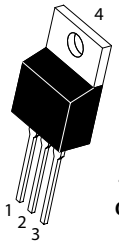
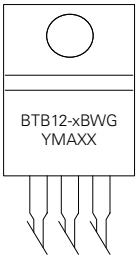
Dimensions



Part Marking System



TO–220AB
CASE 221A
STYLE 12



x =6 or 8
Y =Year
M =Month
A =Assembly Site
XX =Lot Serial Code
G =Pb-Free Package

Dim	Inches		Millimeters	
	Min	Max	Min	Max
A	0.590	0.620	14.99	15.75
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
H	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

1. Dimensioning and tolerancing per ansi y14.5m, 1982.
2. Controlling dimension: inch.
3. Dimension z defines a zone where all body and lead irregularities are allowed.

Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	Main Terminal 2

Ordering Information

Device	Package	Shipping
BTB12–600BW3G	TO–220AB (Pb–Free)	1000 Units / Box
BTB12–800BW3G	TO–220AB (Pb–Free)	1000 Units / Box

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